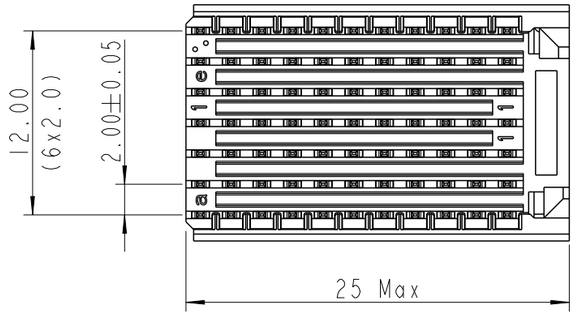
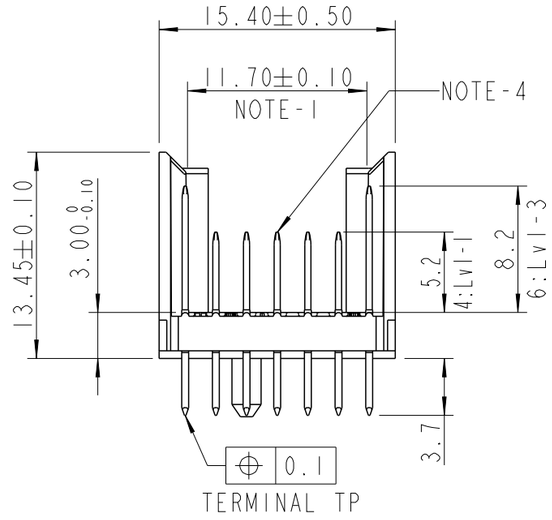
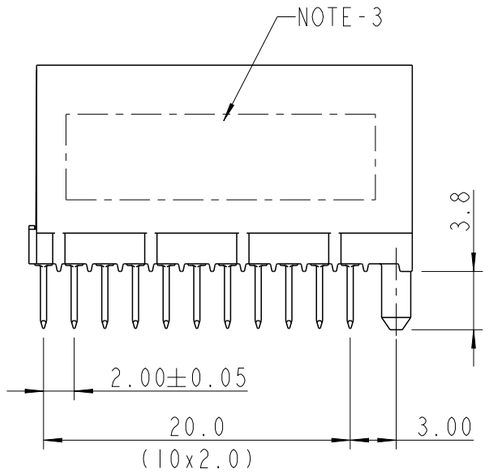
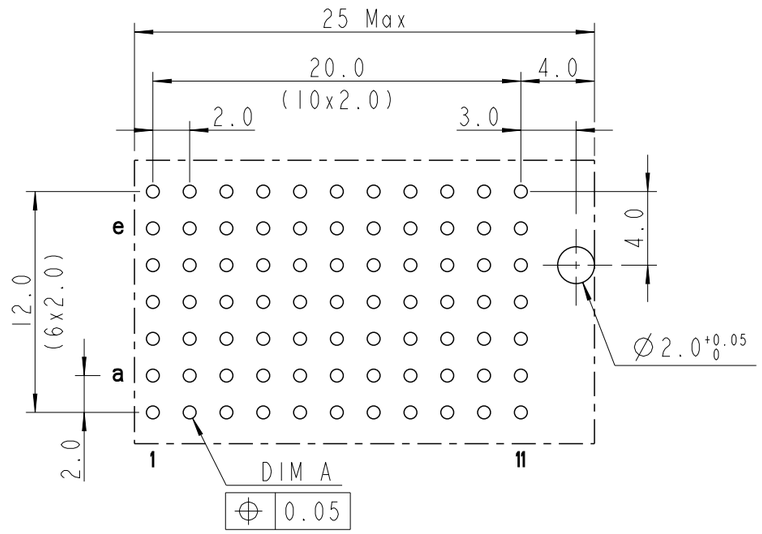
LOADED CONNECTOR ASSEMBLY (For Eg. HM2P09SD5111----)







PCB LAYOUT COMPONENT SIDE



Dim	Finished Hole Dia	Cu Thickness	Sn Thickness	Drilled Hole Dia
A	0.65 - 0.80	0.025 - 0.05	0.008 - 0.012	0.72 - 0.92

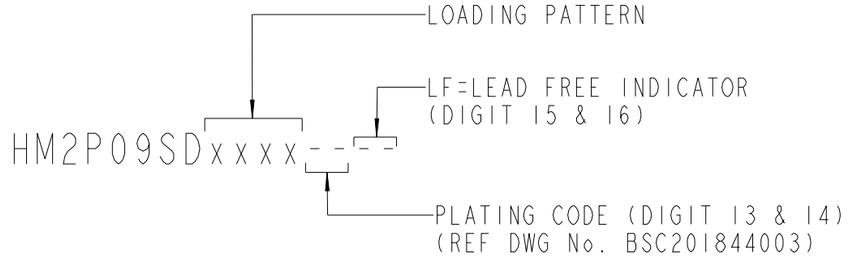
LOADING PATTERN MATING SIDE

Cat No : HM2P09SD5111----

z	01										11
f	6	6	6	6	6	6	6	6	6	6	6
e	4	4	4	4	4	4	4	4	4	4	4
d	4	4	4	4	4	4	4	4	4	4	4
c	4	4	4	4	4	4	4	4	4	4	4
b	4	4	4	4	4	4	4	4	4	4	4
a	4	4	4	4	4	4	4	4	4	4	4
z	6	6	6	6	6	6	6	6	6	6	6

Cat No : HM2P09SD5110----

z	01										11
f	0	0	0	0	0	0	0	0	0	0	0
e	4	4	4	4	4	4	4	4	4	4	4
d	4	4	4	4	4	4	4	4	4	4	4
c	4	4	4	4	4	4	4	4	4	4	4
b	4	4	4	4	4	4	4	4	4	4	4
a	4	4	4	4	4	4	4	4	4	4	4
z	0	0	0	0	0	0	0	0	0	0	0



NOTES :

1. MEASURED AT THE BOTTOM
2. MATERIAL:
   CONTACT : COPPER ALLOY
   HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94 V-0 (BLACK)
3. CONNECTOR PRINTED WITH P/N AND DATE CODE
4. FOR ACTUAL CONTACT LOADING,SEE LOADING PATTERN MATING SIDE.
5. THE SOLDER CONTENT IN THE PASTE SHOULD BE SUFFICIENT TYPICALLY 50% VOLUME PERCENTAGE. THE SCREEN PRINTING PROCESS (ANGLE,SPEED,PRESSURE ETC) MUST BE OPTIMISED SO THAT ENOUGH SOLDER IS AVAILABLE.(PASTE THICKNESS = 0.15MM)
6. THIS PRODUCT (LF) MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004
7. THIS PRODUCT WITHSTANDS 260°C FOR 10 SECS FOR PIN IN PASTE APPLICATION

spec ref	-			dr	Binesh C	2020/11/10	projection
tolerance std ISO 406 ISO 1101	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng	Binesh C	2020/11/10	MM
				chr	-	-	
				appr	Kuriakose, San	2020/11/10	product family MILLIPACS
surface - ISO 1302	linear	0.X	±0.2	Amphenol FCi	title	MILLIPACS TYPE-C STR HDR PIP VERSION	dwg no BSC203204009
		0.XX	±0.1				
		0.XXX	±0.05				
	angular	0°	±1°		cat. no.	HM2P09SDxxxx--LF	Product - Customer Drw

size	scale	rev
A3	2:1	A

ecn no -

rel level **Released**

sheet 1 of 1

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Creo File - REV E - 2016-02-12

PDS: Rev :A

STATUS:Released

Printed: Nov 10, 2020